

SOT996-3

Plastic extremely thin small outline package; no leads; 8 terminals

8 February 2016

Package information

1. Package summary

Terminal position code	D (double)
Package type descriptive code	XSON8
Package type industry code	XSON8
Package style descriptive code	XSON (extremely thin small outline; no leads)
Package style suffix code	NA (not applicable)
Package body material type	P (plastic)
IEC package outline code	- - -
JEDEC package outline code	MO-229
JEITA package outline code	- - -
Mounting method type	S (surface mount)
Issue date	30-3-2011

Table 1. Package summary

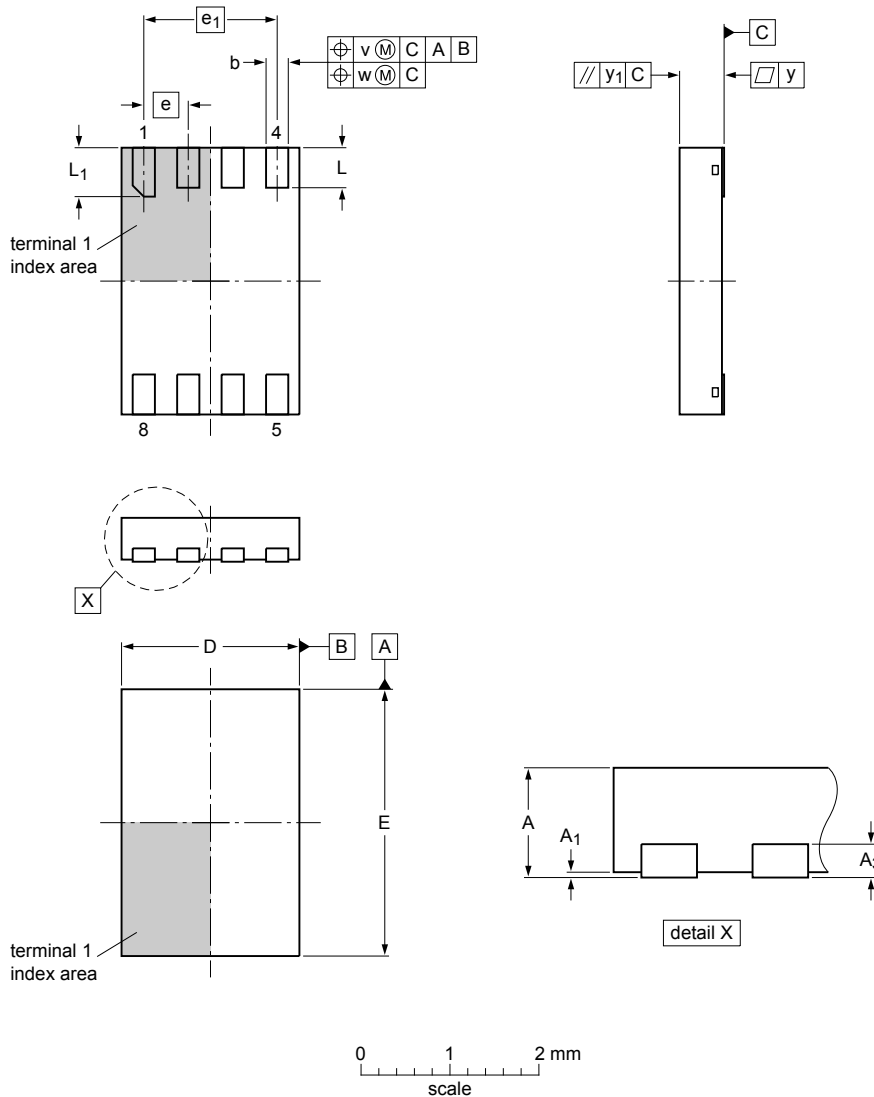
Symbol	Parameter	Min	Typ	Nom	Max	Unit
D	package length	1.9	-	2	2.1	mm
E	package width	2.9	-	3	3.1	mm
A	seated height	[tbd]	-	[tbd]	0.5	mm
e	nominal pitch	-	-	0.5	-	mm
n ₂	actual quantity of termination	-	-	8	-	



2. Package outline

XSON8: plastic extremely thin small outline package; no leads; 8 terminals; body 3 x 2 x 0.5 mm

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Dimensions

Unit ⁽¹⁾	A	A ₁	A ₃	b	D	E	e	e ₁	L	L ₁	v	w	y	y ₁
max	0.5	0.05		0.30	2.1	3.1			0.50	0.60				
mm nom		0.02	0.13	0.25	2.0	3.0	0.5	1.5	0.45	0.55	0.1	0.05	0.05	0.05
min		0.00		0.20	1.9	2.9			0.40	0.50				

Note

1. Plastic or metal protrusions of 0.075 mm maximum per side are not included.

sot996-3_po

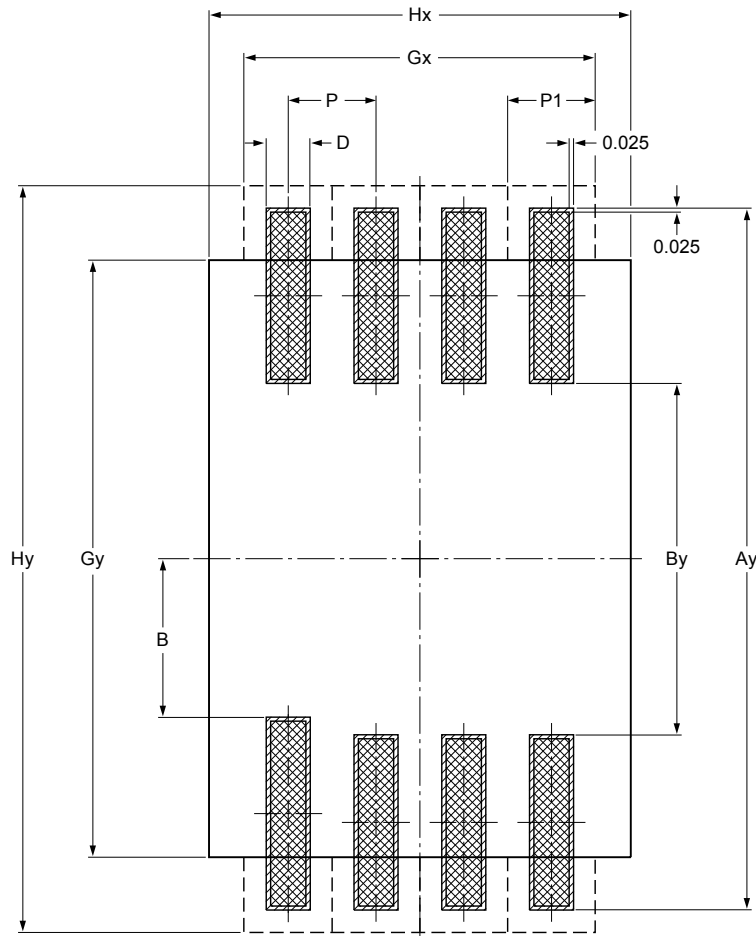
Outline version	References			European projection	Issue date
	IEC	JEDEC	JEITA		
SOT996-3	---	MO-229	---		10-10-07-11-03-30

Fig. 1. Package outline XSON8 (SOT996-3)

3. Soldering

Footprint information for reflow soldering of XSON8 package

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- solder lands placement area
- solder paste occupied area

DIMENSIONS in mm

P	P1	Ay	By	B	D	Gx	Gy	Hx	Hy
0.5	0.5	4	2	0.9	0.25	2	3.4	2.4	4.25

Issue date ~~12-12-18~~
13-01-02

sot996-3_fr

Fig. 2. Reflow soldering footprint for XSON8 (SOT996-3)

4. Legal information

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Date of release: 8 February 2016
